



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Mc CORMACK, MARK FEE RECEIVED
Serial No.: 09/834,273 2001 JUL 12 P 3:00
Filed: 4/12/01
For: METHOD AND STRUCTURE OF
DEPOSITING SOLDER BUMPS
ON A WAFER (99-32)
Group Art Unit: 2812
Attorney Docket No: P53945US0

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TC 1700

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Commissioner for Patents
Washington, D.C. 20231

Sir:

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Respectfully submitted,

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July 9, 2001
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